



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD25N06S2-40		<b>Issued</b>		2. August 2018		
<b>MA#</b>		MA001048192						
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		369.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.550	0.42	0.42	4194	4194
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		582	
	inorganic material	phosphorus	7723-14-0	0.065	0.02		175	
	non noble metal	copper	7440-50-8	215.017	58.16	58.24	581601	582358
wire	non noble metal	aluminium	7429-90-5	0.919	0.25	0.25	2487	2487
encapsulation	organic material	carbon black	1333-86-4	1.273	0.34		3443	
	plastics	epoxy resin	-	22.277	6.03		60258	
	inorganic material	silicondioxide	60676-86-0	103.748	28.06	34.43	280629	344330
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10116	10116
plating	non noble metal	nickel	7440-02-0	0.091	0.02		246	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	247
solder	noble metal	silver	7440-22-4	0.040	0.01		108	
	non noble metal	tin	7440-31-5	0.032	0.01		87	
	non noble metal	lead	7439-92-1	1.528	0.41	0.43	4132	4327
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16	
	non noble metal	copper	7440-50-8	19.177	5.19	5.20	51873	51941
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com